Early Warning System

EIB-20210652

Advanced Semiconductor Silicon Wafer Development



Quick Facts

Countries	Germany
Specific Location	Freiberg
Financial Institutions	European Investment Bank (EIB)
Status	Approved
Bank Risk Rating	U
Voting Date	2022-09-19
Borrower	SILTRONIC AG
Sectors	Industry and Trade
Investment Type(s)	Loan
Loan Amount (USD)	\$ 200.60 million
Project Cost (USD)	\$ 453.37 million



Project Description

According to the EIB, the project relates to the RDI activities for the development of the next generation of hyper pure silicon wafers and ingots for the semiconductor industry as well as the adaptation of the promoter's state-of-the-art ingot production for most advanced wafer types. The project includes RDI activities in the promoter's RDI locations in Germany as well as the extension of the promoter's production facility in Freiberg, Germany, a cohesion region.



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Investment Description

• European Investment Bank (EIB)



Private Actors Description

As stated by Bloomberg, Siltronic AG manufactures hyperpure silicon wafers. The Company offers products including nonpolished and epitaxial coated wafers with different diameter sizes. Siltronic caters its products worldwide for use in computers, smartphones, flat-panel displays, navigation systems, automotive engine control systems, and many other applications.



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Private Actor 1	Private Actor 1 Role	Private Actor 1 Sector	Relation	Private Actor 2	Private Actor 2 Role	Private Actor 2 Sector
-	-	-	-	Siltronic AG	Client	Industry and Trade



Contact Information

No project contacts available at the time of disclosure.

Client - Siltronic AG:

Address: Einsteinstraße 172, 81677 Munich, Germany Email: info@siltronic.com Phone: +49 89 8564-3000 Website: www.siltronic.com/en

ACCESS TO INFORMATION

You can submit an information request for project information at: https://www.eib.org/en/infocentre/registers/requestform/request-form-default.htm

ACCOUNTABILITY MECHANISM OF EIB

The EIB Complaints Mechanism is designed to facilitate and handle complaints against the EIB by individuals, organizations or corporations affected by EIB activities. When exercising the right to lodge a complaint against the EIB, any member of the public has access to a two-tier procedure, one internal - the Complaints Mechanism Office - and one external - the European Ombudsman. A complaint can be lodged via a written communication addressed to the Secretary General of the EIB, via email to the dedicated email address: complaints@eib.org, by completing the online complaint form available at the following address: http://www.eib.org/complaints/form via fax or delivered directly to the EIB Complaints Mechanism Division, any EIB local representation office or any EIB staff. For further details, check:

http://www.eib.org/attachments/strategies/complaints_mechanism_policy_en.pdf

When dissatisfied with a complaint to the EIB Complaints Mechanism, citizens can then turn towards the European Ombudsman. A memorandum of Understanding has been signed between the EIB and the European Ombudsman establishes that citizens (even outside of the EU if the Ombudsman finds their complaint justified) can turn towards the Ombudsman on issues related to 'maladministration' by the EIB. Note that before going to the Ombudsman, an attempt must be made to resolve the case by contacting the EIB. In addition, the complaint must be made within two years of the date when the facts on which your complaint is based became known to you. You can write to the Ombudsman in any of the languages of the European Union. Additional details, including filing requirements and complaint forms, are available at: http://www.ombudsman.europa.eu/atyourservice/interactiveguide.faces



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Bank Documents

• Environmental and Social Data Sheet

Media

• Germany: EIB supports development of Siltronic's next generation of silicon wafers